

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 05/28/2022

Details for "CC430F5123IRGZR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
CC430F5123IRGZR	NIPDAU	Level-3-260C-168 HR	TI MALAYSIA A/T	RGZ 48	7x7x0.9	116.2

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.310314	97.534865	975349	0.267156	2672
Nickel and Its Alloys	Nickel	7440-02-0	0.000002	0.000629	6	0.000002	0
Not Categorized	Proprietary Materials		0.000035	0.011001	110	0.00003	0
Precious Metals	Gold	7440-57-5	0.000164	0.051547	515	0.000141	1
Precious Metals	Palladium	7440-05-3	0.007633	2.39913	23991	0.006571	66
Precious Metals	Silver	7440-22-4	0.000009	0.002829	28	0.000008	0
Sub-Total			0.318157	100	1000000	0.273908	2739
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.048903	2.000017	20000	0.042102	421
Precious Metals	Silver	7440-22-4	1.687139	69	690000	1.452495	14525
Thermoplastics	Epoxy	85954-11-6	0.709087	28.999983	290000	0.610469	6105
Sub-Total			2.445129	100	1000000	2.105065	21051
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	42.644748	99.249999	992500	36.713802	367138
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.111714	0.26	2600	0.096177	962
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.107418	0.250001	2500	0.092479	925
Zinc and Its Alloys	Zinc	7440-66-6	0.103121	0.24	2400	0.088779	888
Sub-Total			42.967001	100	1000000	36.991237	369912
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.735278	95.120052	951201	0.633017	6330
Precious Metals	Gold	7440-57-5	0.006029	0.779948	7799	0.00519	52
Precious Metals	Palladium	7440-05-3	0.031693	4.1	41000	0.027285	273
Sub-Total			0.773	100	1000000	0.665493	6655
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	55.800206	90.5	905000	48.039625	480396
Other Plastics and Rubber	Carbon Black	1333-86-4	0.308288	0.499999	5000	0.265412	2654
Thermoplastics	Epoxy	85954-11-6	5.549192	9	90000	4.777421	47774
Sub-Total			61.657686	100	1000000	53.082458	530825
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	7.993568	100	1000000	6.881839	68818
Sub-Total			7.993568	100	1000000	6.881839	68818
Total			116.154541			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.